Amendments to the specification

On page 2, please amend the first paragraph of the "Summary" section as follows:

A first embodiment of an encapsulated organic electronic device is described. The encapsulated device includes a substrate, an organic electronic device on the substrate, and an epoxy on the substrate that surrounds a perimeter of the organic electronic device. In addition, the encapsulated device also includes an encapsulation lid on the epoxy. The epoxy is a liquid or a gel when it is applied to the encapsulation lid or the substrate, and the epoxy includes a desiccant, and the desiccant can be: barium oxide, calcium oxide, magnesium oxide, cobalt chloride, calcium chloride, calcium bromide, lithium chloride, zinc chloride, zinc bromide, sodium ~~molevular~~ molecular, silicon dioxide, aluminum oxide, calcium sulfate, copper sulfate, potassium carbonate, magnesium carbonate, titanium dioxide, bentonite, acidic clay, montmorillonite, diatomaceous earth silica alumina, zeolite, silica, zirconia, activated carbon, or a mixture thereof.

On page 3, please amend the first paragraph of the "Detailed Description" section as follows:

In a first embodiment of the invention, an organic electronic device is encapsulated using an epoxy that includes a desiccant. The epoxy is around a perimeter of the organic electronic device. The epoxy bonds an encapsulation lid to a substrate and also absorbs oxygen and/or moisture. The desiccant in the epoxy can be any one of: barium oxide, calcium oxide, magnesium oxide, cobalt chloride, calcium chloride, calcium bromide, lithium chloride, zinc chloride, zinc bromide, sodium ~~molevular~~ molecular, silicon dioxide, aluminum oxide, calcium sulfate, copper sulfate, potassium carbonate, magnesium carbonate, titanium dioxide, bentonite, acidic clay, montmorillonite, diatomaceous earth silica alumina, zeolite, silica, zirconia, activated carbon, or a mixture thereof.

Please amend the last paragraph on page 4 that continues to the top of page 5 as follows:

The desiccant within the epoxy 161 can be any one of: barium oxide, calcium oxide, magnesium oxide, cobalt chloride, calcium chloride, calcium bromide, lithium chloride, zinc chloride, zinc bromide, sodium ~~molevular~~ molecular, silicon dioxide, aluminum oxide, calcium sulfate, copper sulfate, potassium carbonate, magnesium carbonate, titanium dioxide, bentonite, acidic clay, montmorillonite, diatomaceous earth silica alumina, zeolite, silica, zirconia, activated carbon, or a mixture thereof.

On page 8, please amend the paragraph starting at line 6 of the specification as follows:

A desiccant ring 218 is on the encapsulation lid 164. The desiccant ring 218 is evaporated onto the encapsulation ~~ring~~ lid 164. The desiccant ring 218 is made of a reactive metal (e.g., [[,]]alkaline-earth metals (i.e., metals in Group 1A of the Periodic Table)) or a reactive oxide (e.g., alkaline-earth metal oxides (i.e., metals in Group IIA of the Periodic Table)). For example, the desiccant ring 218 can be made of barium or calcium. The desiccant ring 218 absorbs the moisture and/or oxygen that have entered the device package. The desiccant ring 218 is not used to bond the encapsulation lid 164 to the substrate 158. Preferably, the desiccant ring 218 has a height that ranges from 300 nm up to 1 micron. Since most of the reactive gasses enter the device package by permeating through the epoxy 215, the desiccant ring 218 is placed near the epoxy 215 to absorb the moisture and/or oxygen entering the device package. Also, the desiccant ring 218 is near the edges of the electronic device to better protect the edges of the device's cathode strips. The reactive gasses can attack the edges of the cathode strips causing detrimental effects such as pixel shrinkage.